Amendments to the Specification

Please enter the Substitute Specification (Clean Version) attached at the backside of this paper which corresponds to the Substitute Specification (Marked Up Version) filed in the Office on January 4, 2006.

Please amend the Abstract at page 9 of the Substitute Specification (Clean Version) enclosed with the following revised Abstract:

A The invention relates to a semiconductor substrate or wafer inspection device [[.]] The device comprises for detecting defects on wafer surfaces includes an air-cushion stage which can be displaced in two directions (X,Y) that are perpendicular to one another. Several air nozzles are provided for this purpose. At least one valve is connected to at least one electric control unit, the valve being configured in such a way that a normal pressure prevails in the air nozzles when the electric control unit delivers a corresponding signal.